

Title (en)
POLYAMIDE COMPOSITION FOR MOLDING

Title (de)
POLYAMIDFORMMASSEN

Title (fr)
COMPOSITION POLYAMIDE POUR MOULAGE

Publication
EP 1137713 A1 20011004 (EN)

Application
EP 99971014 A 19991022

Priority
• JP 30283398 A 19981023
• US 9924767 W 19991022

Abstract (en)
[origin: WO0024830A1] A polyamide composition for molded products having thin-wall parts and for connectors for use in automobiles, containing:
A) 100 wt parts of a semi-aromatic polyamide having a melting point of 280 to 320 DEG C and a glass transition temperature of 95 to 115 DEG C, wherein the amount of aromatic monomer constituting the polyamide is at least 30 mol %, and B) 1 to 70 wt parts of an impact resistance agent composed mainly of a modified polyolefin that has been graft-modified by means of a carboxylic acid or a carboxylic anhydride.

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C08L 77/06; H01B 3/30; H01R 13/46; C08L 77/00

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Citation (search report)
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